



In re application of : Mitsusuke Kyogoku, et al.
 App. No. : 09/650,122
 Filed : August 29, 2000
 For : SEALING MECHANISM OF
 MULTI-CHAMBER LOAD-
 LOCKING DEVICE
 Examiner : Ram N. Kackar
 Art Unit : 1763

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Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	4	—	20	= 0 ×	\$18	= \$0
Independent Claims	1	—	3	= 0 ×	\$84	= \$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$0

- (X) Amendment in seven (7) pages.
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Kyogoku et al.) Group Art Unit 1763
Appl. No. : 09/650,122)
Filed : August 29, 2000)
For : SEALING MECHANISM OF)
MULTI-CHAMBER LOAD-)
LOCKING DEVICE)
Examiner : R. Kackar)

AMENDMENT

Assistant Commissioner for Patents

Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed July 22, 2002 (Paper number 6), please amend the above-captioned application as follows:

IN THE CLAIMS:

Please cancel Claims 3, 6, and 11 without prejudice.

Please amend Claim 1 as follows:

Claim 1 has been amended as follows:

1. (Thrice amended) A multi-chamber load-locking device for transferring wafers, said device having an interior divided into (i) an upper chamber and (ii) a lower chamber, and (iii) an intermediate section located between the upper chamber and the lower chamber, which is for loading/unloading wafers,

said device comprising (a) a single divider plate having an upper side and a lower side, both of which are for temporarily supporting wafers, said plate moving reciprocally between an upper position and a lower position, wherein the plate divides and seals the upper chamber from the intermediate section and the lower chamber at the upper position, and the plate divides and

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